

50
B2
A

1 2. (Once amended) The apparatus of claim 1, wherein said
2 metal-oxide-semiconductor includes a gate region material with a work
3 function less than -0.56 volts.

1 3. (Once amended) The apparatus of claim 2, wherein said
2 gate region material is platinum silicate.

1 4. (Once amended) The apparatus of claim 2, wherein said
2 gate region material is selected from the group consisting of tantalum
3 nitrate, iridium, nickel, and arsenic.

1 5. (Unamended) The apparatus of claim 1, wherein said
2 metal-oxide-semiconductor transistor includes a heavily-doped
3 substrate area.

1 6. (Unamended) The apparatus of claim 1, wherein said
2 metal-oxide-semiconductor transistor is a p-channel device.

1 7. (Unamended) The apparatus of claim 1, wherein said
2 metal-oxide-transistor is an n-channel device.

1 15. (Unamended) An apparatus, comprising:
2 means for shifting a flat band magnitude in a metal-oxide-
3 semiconductor transistor;
4 means for coupling a gate electrode of said metal-oxide-
5 semiconductor transistor to a positive voltage source;
6 and
7 means for coupling a source electrode, a drain electrode, and a
8 substrate electrode of said metal-oxide-
9 semiconductor transistor to a negative voltage
10 source.

500
P2 BX
1 16. (Once amended) The apparatus of claim 15, wherein said
2 means for shifting includes a gate region with a material whose work
3 function is less than - 0.56 volts.

1 17. (Unamended) The apparatus of claim 16, wherein said
2 material is platinum silicate.

1 18. (Unamended) The apparatus of claim 16, wherein said
2 material is selected from the group consisting of tantalum nitrate,
3 iridium, nickel, and arsenic.

1 19. (Unamended) The apparatus of claim 15, wherein said
2 means for shifting includes a substrate which is heavily-doped.